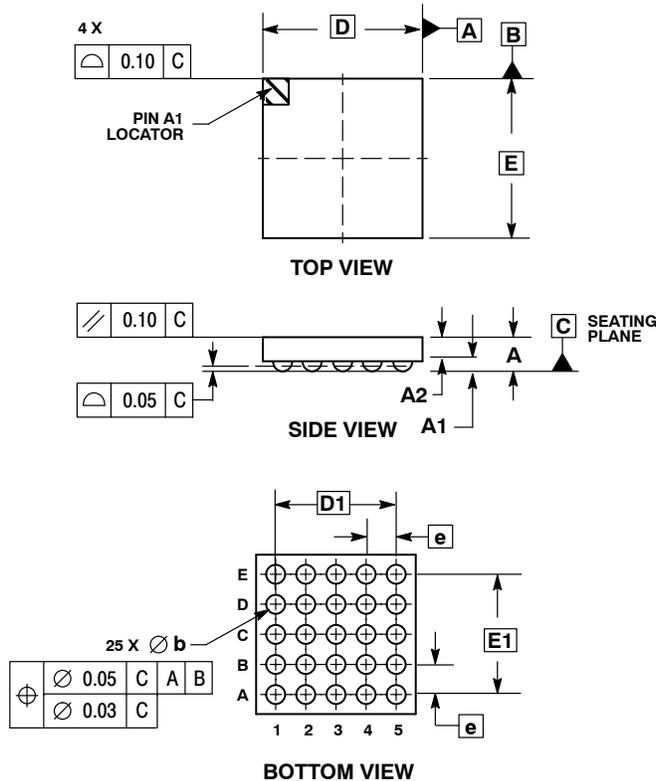


A1

SCALE 4:1

FLIP-CHIP-25 CSP
CASE 499G
ISSUE B

DATE 03 MAY 2005

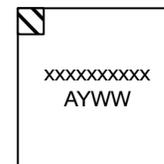


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.700
A1	0.210	0.270
A2	0.380	0.430
D	2.650 BSC	
E	2.650 BSC	
b	0.290	0.340
e	0.500 BSC	
D1	2.000 BSC	
E1	2.000 BSC	

GENERIC
MARKING DIAGRAM*



- xxxxxx = Specific Device Code
- A = Assembly Location
- Y = Year
- WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "μ", may or may not be present.

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DESCRIPTION:	FLIP-CHIP-25 CSP, 0.265 *0.265 MM, 0.500 PITCH	PAGE 1 OF 1

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